

HF

Halogen Free

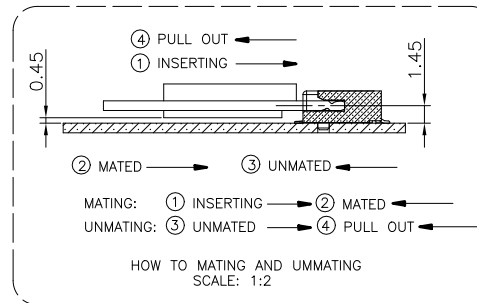
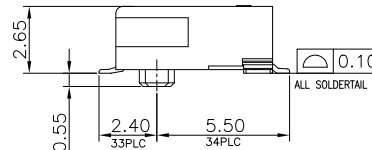
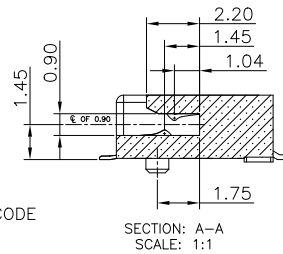
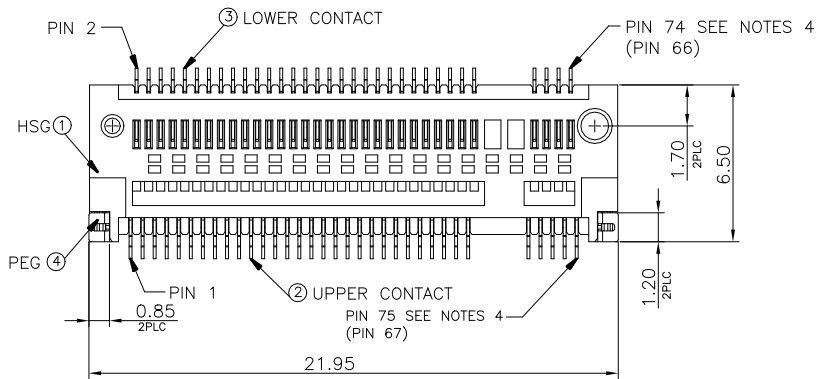
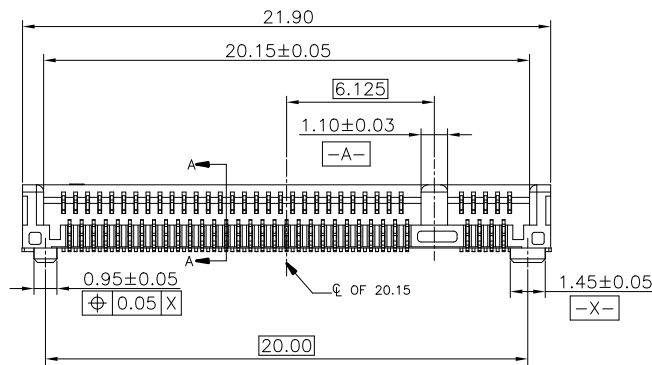
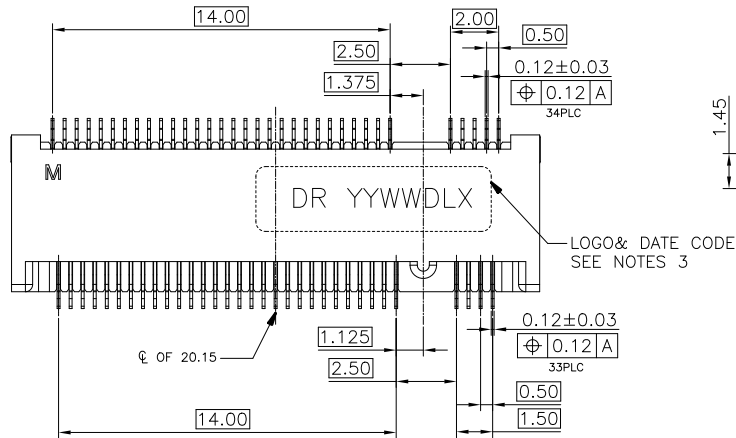
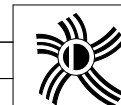


TABLE 1:

PART NUMBER	DESCRIPTION
5621D3-040H1B11R	Au G/F ON CONTACT AREA
5621D3-040H2B11R	Au 5u" ON CONTACT AREA
5621D3-040H3B11R	Au 10u" ON CONTACT AREA
5621D3-040H4B11R	Au 15u" ON CONTACT AREA
5621D3-040H5B11R	Au 30u" ON CONTACT AREA

DIM	TOL	DIM	TOL
X.	±0.30	X.	±2*
.X	±0.25	.X	±1*
.XX	±0.20		



DEREN
SHENZHEN DEREN ELECTRONIC CO., LTD

DRAW NO.
SC2309632-4

REV. A

C-DWG:	TY	DATE	TITLE:NGFF 2.65H KEY M GEN4 DR Logo
DESIGN:	Sid Guo	2024.01.23	P/N: SEE TABLE 1
CHECK:	Mike Chen	2024.01.23	SHEET: 1/3
APPROVAL:	Bill Lin	2024.01.23	SCALE: N/A UNIT: mm

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL RELEASE	2024.01.23	Sid Guo

NOTES:

PRODUCT MEETS CONTROLLED SUBSTANCES SPEC. ROHS 2.0

1.MATERIAL:

- 1.1 HOUSING:LCP, UL94V.0; COLOR: BLACK
- 1.2 CONTACT PHOSPHOR BROZNE.
- 1.3 SOLDER PEG AND LATCH:STAINLESS STEEL.

2.FINISH:

- 2.1 CONTACT: 50u" MIN NICKEL UNDERPLATED ALL OVER.
GOLD FLASH PLATING ON SOLDER TAIL.
GOLD PLATING (SEE NOTE 9) ON CONTACT AREA.
- 2.2 SOLDER PEG:
MATTE TIN 100u" MIN. AND NICKEL 50u" MIN UNDERPLATED.

3.LOGO&DATE CODE:

- LOGO: DR OR DEREN
DATECODE: YYWDLX
YY: YEAR (09: 2009)
WW: WEEK (25: THE 25TH WEEK)
D: DAY (1~7: SUNDAY~SATURDAY)
L: LINE NUMBER OF ASSEMBLY (A: LINE A)
X: MANUFACTURE CODE

4.REFLOW SOLDER CAPABLE TO 260°C 10 SEC.

5.ELECTRICAL CHARACTERISTICS :

- 5.1 CURRENT RATING:0.5AMP.
- 5.2 CONTACT RESISTANCE:55 MILLIOHMS MAX. INITIAL,
20 MILLIOHMS MAX. CHANGE AFTER TEST.
- 5.3 IMPEDANCE:85±10% OHMS
- 5.4 INSULATION RESISTANCE:500 MEGOHMS MIN. INITIAL
100 OHM MIN. CHANGE AFTER TEST.
- 5.5 DIELECTRICAL WITHSTAND VOLTAGE:300V AC
MIN.AT SEA LEVEL.

6.MECHANICAL CHARACTERISTICS:

- 6.1 INSERTION FORCE:20N MAX.PER CONTACT PAIR.
- 6.2 DURABILITY:60 MATING AND UNMATING CYCLES.
- 6.3 CONTACT RETENTION FORCE:0.1kgf

7.ENVIRONMENTAL CHARACTERISTICS:

- OPERATING TEMPERATURE RANGE:40°C TO +80°C.

8.RECOMENDED STENCIL THICKNESS:0.12MM MIN.

9.PART NUMBER DESCRIPTION:

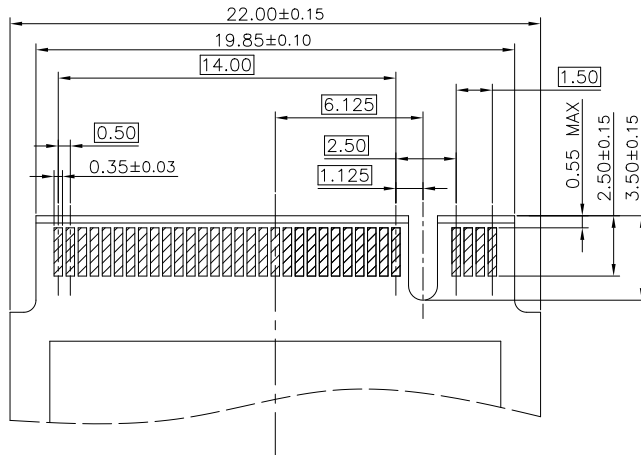
5621D3-040 H X B 1 1 R

- PACKING CODE:
R: EMBOSS WIDTH 44mm, SLOT BACKWARD
Logo:
0:No Logo
1:DR Logo
Color:
1:Black
2:White
KEY TYPE:
B: KEY M
PLATING CODE:
1: AuGF 2: Au5u"
3: Au10u" 4: Au15u"
5: Au30u"
HALOGEN CODE:
H:HALOGEN FREE

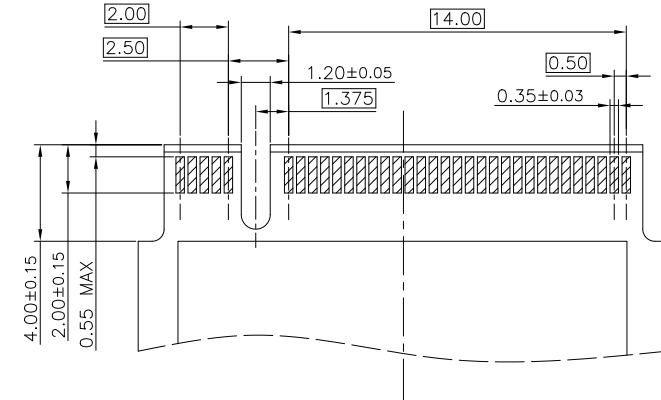
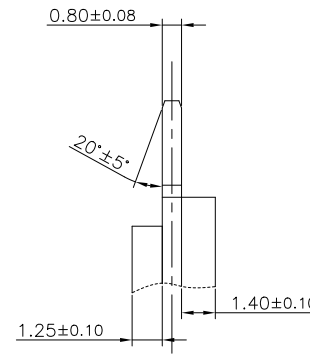
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PLUG PCB

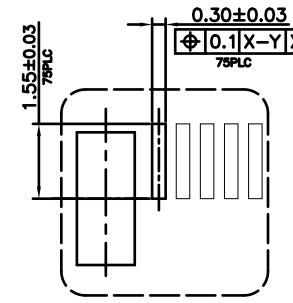
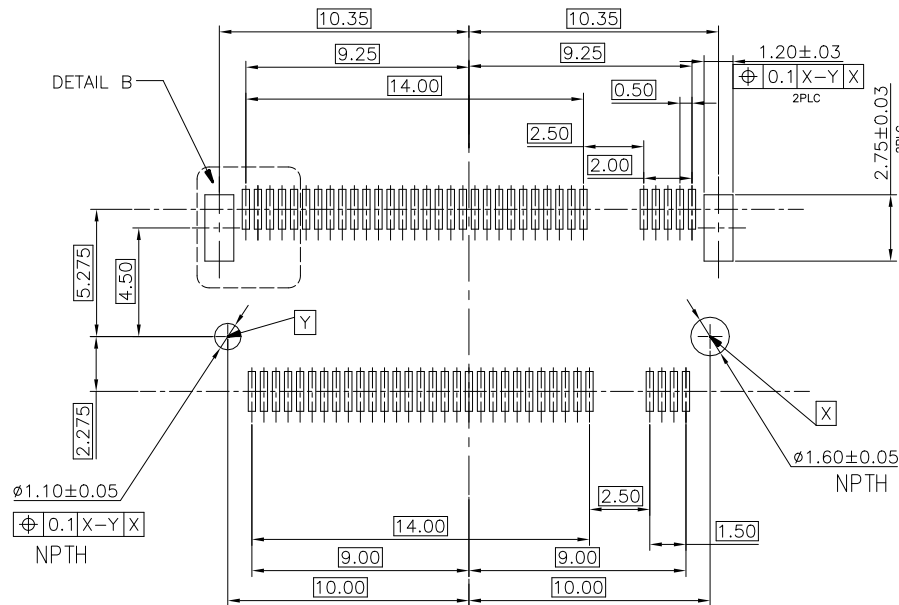


BOTTOM SIDE



TOP SIDE

RECOMMENDED PCB LAYOUT(TOP VIEW)



DETAIL B
SCALE 2:1



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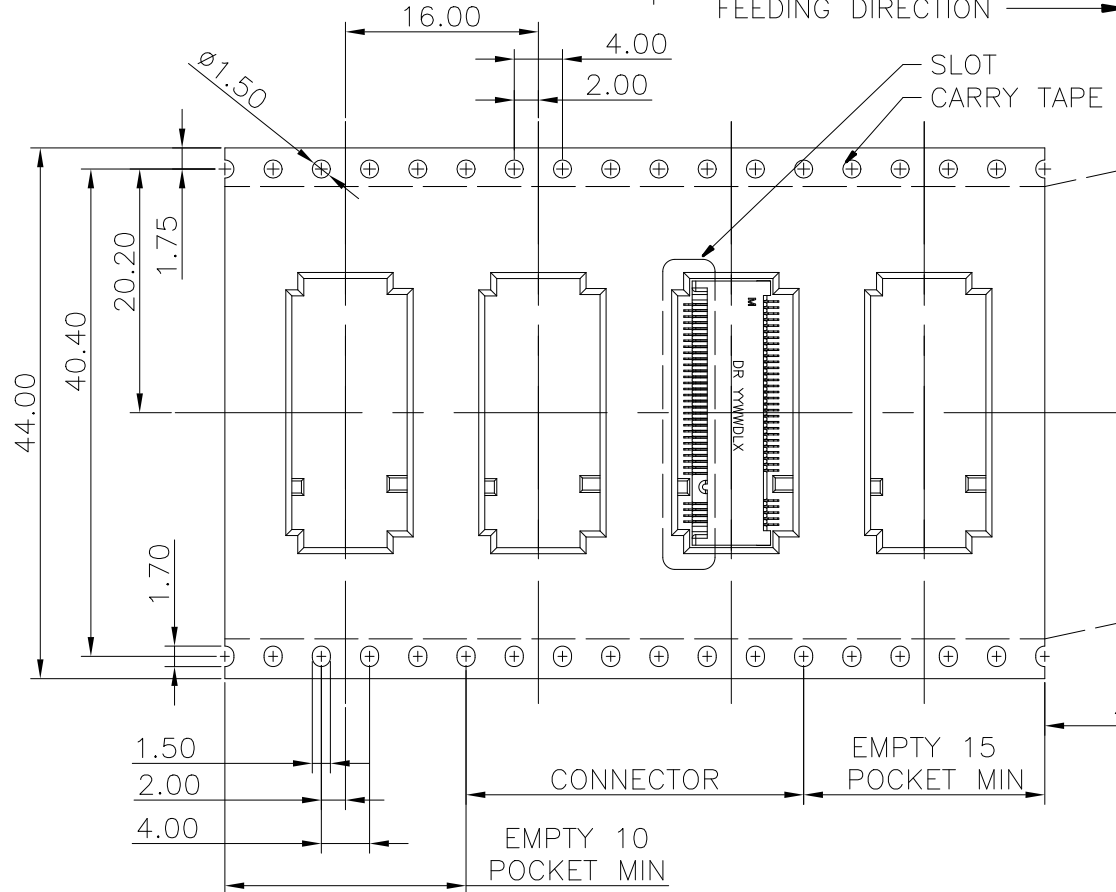
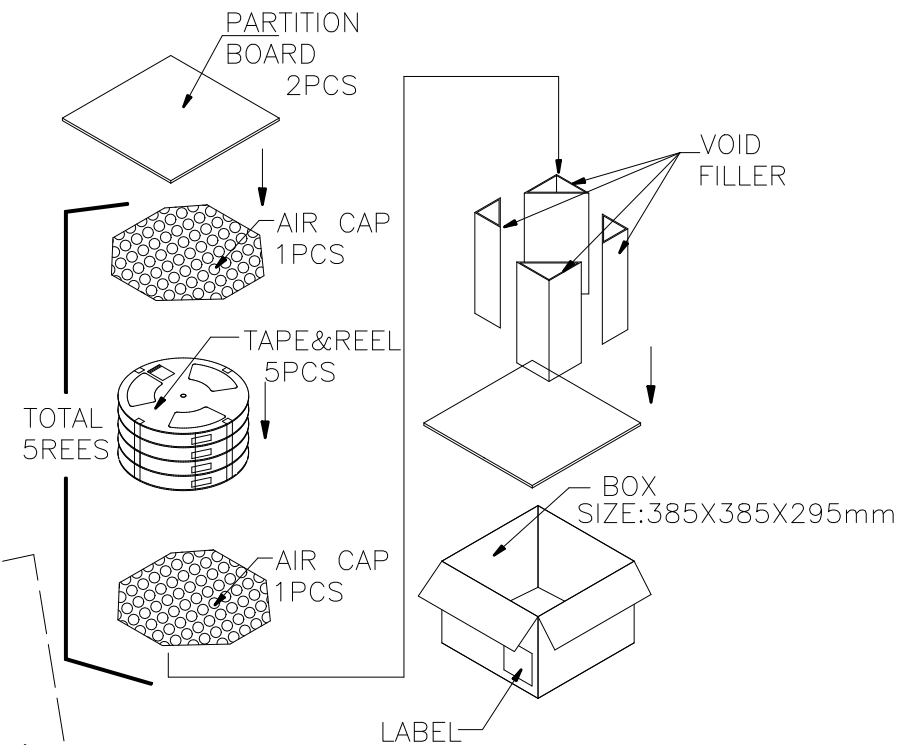
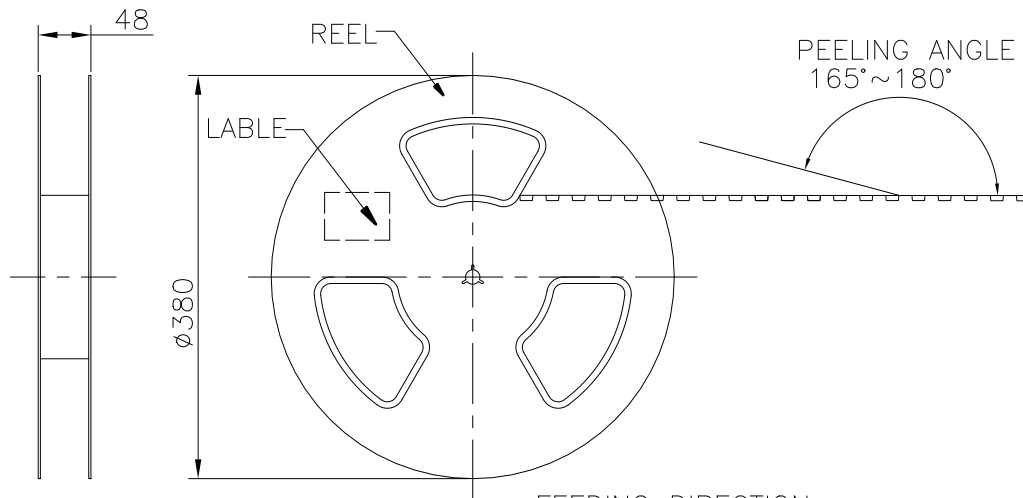
DIM	TOL	DIM	TOL
X	±0.20	X	±2°
.X	±0.10	.X	±1°
.XX	±0.05		
		REV.	A

DEREN				SHENZHEN DEREN ELECTRONIC CO., LTD			
C-DWG:	TY	DATE	TITLE: NGFF 2.65H KEY M GEN4 DR Logo				
DESIGN:	Sid Guo	2024.01.23	P/N: SEE TABLE 1				
CHECK:	Mike Chen	2024.01.23	SHEET:	2/3			
APPROVAL:	Bill Lin	2024.01.23	SCALE:	N/A	UNIT:	mm	

HF

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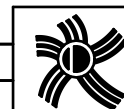
EMBOSS WIDTH 44mm, SLOT BACKWARD



COVER TAPE

1500	5	7500
PCS/ TAPE	REELS/ BOX	PCS/BOX

DIM	TOL	DIM	TOL
x	±0.30	x	±2'
.x	±0.20	.x	±1'
.xx	±0.15		



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TITLE: NGFF 2.65H KEY M GEN4 DR Logo
P/N: SEE TABLE 1
SHEET: 3/3
SCALE: N/A
UNIT: mm